Takatori
Global Innovation "Plus One"

MODEL

ATRM-2200G

Fully Automatic Backgrind Tape Removal System

Outline

The ATRM-2200 is the ideal system for removing lamination tape from wafers, following the backgrind process.

Features

- Thin wafers down to 150 microns
- Warped wafer
- Every other cassette slot applicable
- Integrated UV unit (optional)
- Can be made to accommodate special wafers and special tapes

Specification		ATRM-2200
Throughput		70 wafers/hour (Depend on data setting)
Wafer Size		4 inch、5 inch、6 inch、8 inch(4・5・6 inch or 5・6・8 inch)
Tape Width		4・5・6 inch :W 38 mm 、8 inch :W 50・75 mm
Utilities	Power	AC100V Single phase 50／60Hz 1.5 KVA
	Air	Pressure 0.5Mpa 90Nl/min
	Vacuum sourse	—74Kpa
Dimensions		D 1,025 × W 1,100 × H 1,650mm
Weight		400 kg

System appearance and specifications are subject to change without prior notice from the supplier.

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